Optical Interconnects

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Message from the Guest Editor

Optical Interconnect technologies are rapidly gaining momentum in HPC and DataCenter architectures, aiming at enabling an energy-efficient transition to Exascale processing systems. The recent commercialization of mid-board optical subassemblies and silicon photonic transceiver modules confirms the benefits of bringing optics closer to the processor and memory chip modules, while world-wide efforts for new Rack-Scale and Disintegrated Computing architectural schemes rely on the extensive use of forward-looking optical interconnect platforms. The main purpose of this Special Issue is to consolidate recent research and the most important advances along all relevant technologies and architectures in the field of optical interconnects.

Prof. Nikos Pleros
Guest Editor

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Special Issue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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